<ul> <li>Member of the Texas Instruments</li> <li>Widebus™ Family</li> </ul>	DL OR DGG PACKAGE (TOP VIEW)		
<ul> <li>EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process</li> </ul>	1 <del>OE</del> 1 48 2 <del>OE</del> 1Y1 2 47 1A1		
<ul> <li>Output Ports Have Equivalent 26-Ω Series Resistors, So No External Resistors Are Required</li> </ul>	1Y2 3 46 1A2 GND 4 45 GND 1Y3 5 44 1A3		
<ul> <li>Typical V<sub>OLP</sub> (Output Ground Bounce)</li> <li>&lt; 0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C</li> </ul>	1Y4 6 43 1A4 V <sub>CC</sub> 7 42 V <sub>CC</sub>		
<ul> <li>Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)</li> <li>2 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C</li> </ul>	2Y1		
<ul> <li>Power Off Disables Outputs, Permitting Live Insertion</li> </ul>	GND 10 39 GND 2Y3 11 38 2A3		
<ul> <li>Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V<sub>CC</sub>)</li> </ul>	2Y4   12   37   2A4 3Y1   13   36   3A1 3Y2   14   35   3A2 GND   15   34   GND		
<ul> <li>ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)</li> </ul>	3Y3		
<ul> <li>Latch-Up Performance Exceeds 250 mA Per JESD 17</li> </ul>	4Y1		
<ul> <li>Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors</li> </ul>	GND 21 28 GND 4Y3 22 27 4A3 4Y4 23 26 4A4		
Package Options Include Plastic 300-mil     Shrink Small-Outline (DL) and Thin Shrink	4 <del>0E</del> [ 24 25 ] 3 <del>0E</del>		

NOTE: For tape and reel order entry:

The DGGR package is abbreviated to GR.

Small-Outline (DGG) Packages

#### description

This 16-bit buffer/driver is designed for 1.65-V to 3.6-V V<sub>CC</sub> operation.

The SN74LVCH162244A is designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The device can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. It provides true outputs and symmetrical active-low output-enable  $(\overline{OE})$  inputs.

The outputs, which are designed to sink up to 12 mA, include equivalent  $26-\Omega$  resistors to reduce overshoot and undershoot.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.



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#### description (continued)

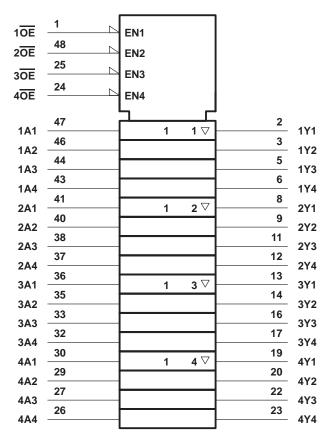
To ensure the high-impedance state during power up or power down,  $\overline{\text{OE}}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVCH162244A is characterized for operation from -40°C to 85°C.

### FUNCTION TABLE (each 4-bit buffer)

INP	JTS	OUTPUT		
OE	Α	Υ		
L	Н	Н		
L	L	L		
Н	Χ	Z		

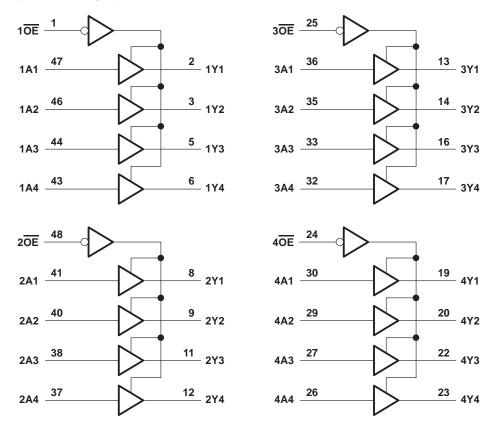
### logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



#### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	
Voltage range applied to any output in the high-impedance or power-off state, VO	
(see Note 1)	
Voltage range applied to any output in the high or low state, VO	
(see Notes 1 and 2)	$\dots$ -0.5 V to V <sub>CC</sub> + 0.5 V
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–50 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Continuous output current, IO	±50 mA
Continuous current through each V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 3): DGG package	89°C/W
DL package	94°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The value of V<sub>CC</sub> is provided in the recommended operating conditions table.
  - 3. The package thermal impedance is calculated in accordance with JESD 51.



### SN74LVCH162244A **16-BIT BUFFER/DRIVER** WITH 3-STATE OUTPUTS SCAS545G - OCTOBER 1995 - REVISED JUNE 1999

#### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
VCC	Supply voltage	Operating	1.65	3.6	V	
		Data retention only	1.5		V	
	High-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>			
$V_{IH}$		V <sub>CC</sub> = 2.3 V to 2.7 V	1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
		V <sub>CC</sub> = 1.65 V to 1.95 V		0.35 × V <sub>CC</sub>		
$V_{IL}$	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		V <sub>CC</sub> = 2.7 V to 3.6 V		0.8		
٧ <sub>I</sub>	Input voltage	<u>.</u>	0	5.5	V	
v <sub>O</sub>	Output voltage	High or low state	0	VCC	V	
		3-state	0	5.5	V 	
	High-level output current	V <sub>CC</sub> = 1.65 V		-2		
la		V <sub>CC</sub> = 2.3 V		-4	A	
ЮН		V <sub>CC</sub> = 2.7 V		-8	mA	
		V <sub>CC</sub> = 3 V		-12		
	Low-level output current	V <sub>CC</sub> = 1.65 V		2		
lOL		V <sub>CC</sub> = 2.3 V	V <sub>CC</sub> = 2.3 V		1	
		V <sub>CC</sub> = 2.7 V		8	mA	
		V <sub>CC</sub> = 3 V		12		
Δt/Δν	Input transition rise or fall rate	0	10	ns/V		
TA	Operating free-air temperature	-40	85	°C		

NOTE 4: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST C	ONDITIONS	Vcc	MIN	TYPT MAX	UNIT		
	I <sub>OH</sub> = -100 μA		1.65 V to 3.6 V	V <sub>CC</sub> -0.:	2			
	$I_{OH} = -2 \text{ mA}$		1.65 V	1.2		]		
	I <sub>OH</sub> = -4 mA	2.3 V	1.7					
Voн	10H = -4 IIIA		2.7 V	2.2		V		
	$I_{OH} = -6 \text{ mA}$		3 V	2.4				
	$I_{OH} = -8 \text{ mA}$		2.7 V	2				
	$I_{OH} = -12 \text{ mA}$		3 V	2				
	I <sub>OL</sub> = 100 μA		1.65 V to 3.6 V		0.2			
	$I_{OL} = 2 \text{ mA}$		1.65 V		0.45			
	I <sub>OL</sub> = 4 mA		2.3 V		0.7			
VOL	10L = 4111A		2.7 V		0.4	V		
	$I_{OL} = 6 \text{ mA}$	I <sub>OL</sub> = 6 mA			0.55			
	$I_{OL} = 8 \text{ mA}$	2.7 V		0.6				
	I <sub>OL</sub> = 12 mA	3 V		0.8				
ΙĮ	$V_{I} = 0 \text{ to } 5.5 \text{ V}$		3.6 V		±5	μΑ		
	V <sub>I</sub> = 0.58 V	1.65 V	‡					
	V <sub>I</sub> = 1.07 V	1.05 V	‡					
	$V_1 = 0.7 V$	2.3 V	45		μΑ			
I <sub>I(hold)</sub>	V <sub>I</sub> = 1.7 V		-45					
	$V_{I} = 0.8 V$	3 V	75					
	V <sub>I</sub> = 2 V	V <sub>I</sub> = 2 V				]		
	V <sub>I</sub> = 0 to 3.6 V§		3.6 V		±500			
l <sub>off</sub>	$V_I$ or $V_O = 5.5 V$		0		±10	μΑ		
loz	$V_0 = 0 \text{ to } 5.5 \text{ V}$		3.6 V		±10	μΑ		
loo	$V_I = V_{CC}$ or GND	I <sub>O</sub> = 0	3.6 V		20	μА		
lcc	$3.6 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}^{\P}$	710=0	3.0 V		20	μΑ		
ΔlCC	One input at V <sub>CC</sub> – 0.6 V,	Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V		500	μΑ		
Ci	$V_I = V_{CC}$ or GND		3.3 V		5.5	pF		
Co	$V_O = V_{CC}$ or GND		3.3 V		6	pF		

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

# switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)				V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V	
	(INFOT)	(001701)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	А	Υ	‡	‡	‡	‡		5.6	1.1	4.4	ns
t <sub>en</sub>	ŌE	Υ	‡	‡	‡	‡		6.9	1	5.5	ns
t <sub>dis</sub>	ŌĒ	Υ	‡	‡	‡	‡		6.8	1.8	6.3	ns

<sup>‡</sup> This information was not available at the time of publication.



<sup>&</sup>lt;sup>‡</sup> This information was not available at the time of publication.

<sup>§</sup> This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

<sup>¶</sup> This applies in the disabled state only.

### SN74LVCH162244A 16-BIT BUFFER/DRIVER WITH 3-STATE OUTPUTS SCAS545G - OCTOBER 1995 - REVISED JUNE 1999

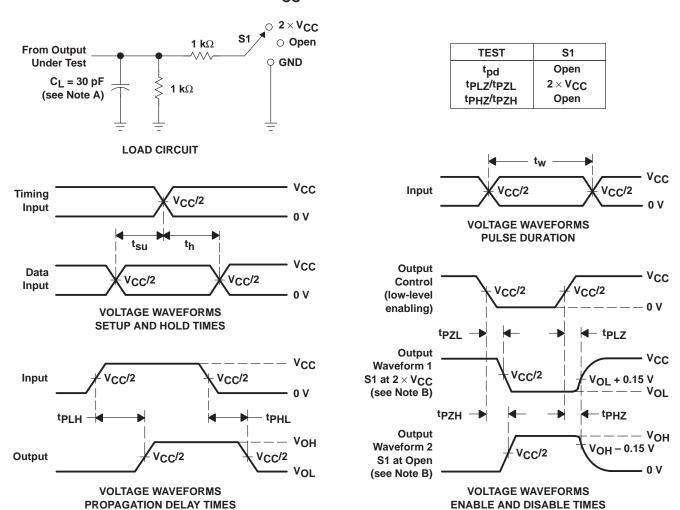
### operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V ± 0.15 V	V <sub>CC</sub> = 2.5 V ± 0.2 V	V <sub>CC</sub> = 3.3 V ± 0.3 V	UNIT		
			CONDITIONS	TYP	TYP	TYP	]	
Power dissipation capacitance		Outputs enabled	f = 10 MHz	†	†	35	pF	
□ <sup>Opa</sup>	per buffer/driver	Outputs disabled	1 = 10 MH2	†	†	4	pr	

<sup>†</sup>This information was not available at the time of publication.



## PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$

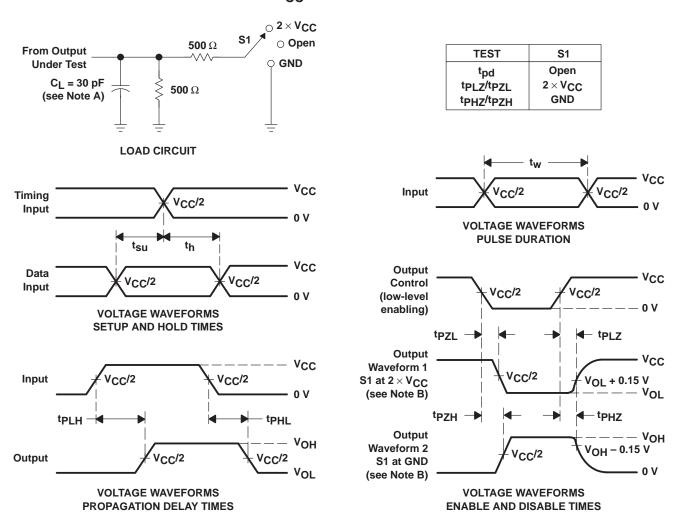


NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O$  = 50  $\Omega$ ,  $t_f \leq$  2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

## PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



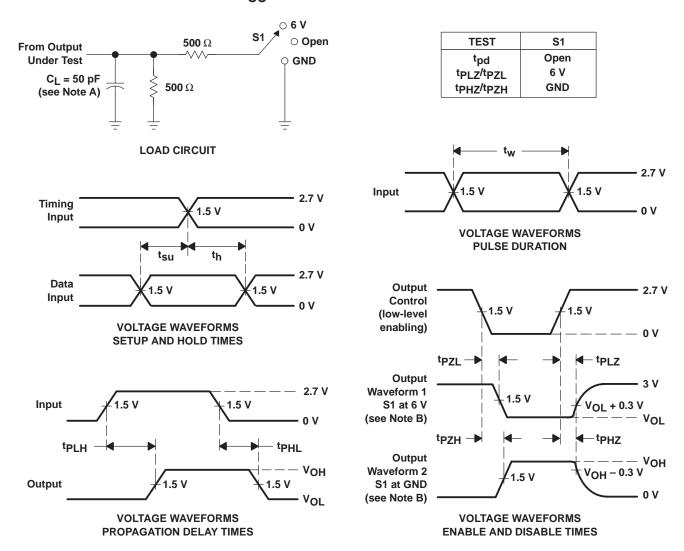
NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50~\Omega$ ,  $t_f \leq$  2 ns,  $t_f \leq$  2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



## PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.7 \text{ V}$ AND 3.3 V $\pm$ 0.3 V



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms



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